## WHAT IS CLAIMED

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A strapless lead frame/heat slug combination, comprising:

a plurality of lead frame leads distributed around a semiconductor die mount area, and extending into the area normally occupied by the lead frame strap; and

a heat slug attached under the lead frame with tape providing the die mount area.

2. The strapless lead frame according to Claim 1, wherein the semiconductor die has four sides and the lead frame leads are evenly distributed on each of the four sides.

3. The strapless lead frame according to Claim 1, wherein the lead frame has four sides and two of said four sides have a different number of leads from two other sides.

The strapless lead frame according to Claim 1, where in said semiconductor die has a different number of bond pads on adjacent sides, and at least one of said bond pads is attached to a bond wire attached to a lead frame lead on a side of the lead frame adjacent to the side of the semiconductor die on with the bond pad is located.

5. A strapless lead frame for use with heat slug packages, comprising:

a plurality of lead frame leads distributed around a semiconductor die mount area, and extending into the area normally occupied by the lead frame strap;

a heat slug attached under the lead frame with tape providing a rectangular die mount area, there being the same number of lead frame leads on opposites sides of the lead frame and a different number of lead frame leads on adjacent sides of the lead frame.

6. The strapless lead frame according to Claim 5, including a semiconductor die with a different number of bond pads on adjacent sides and the same number of bond pads on opposite sides, and at least one of said bond pads is attached to a bond wire attached to a lead frame lead on a side of the lead frame adjacent to the side of the semiconductor die on with the bond pad is located.